A1 INDEX

27

24.3
23.7

⌖ 0.2Ⓜ A B C

C

B

4X ⌓ 0.2

24.3
23.7

⌖ 0.2Ⓜ A B C

27

TOP VIEW

SEATING PLANE

4

A

272X ⌓ 0.2 A

// 0.35 A

19X 1.27

1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20

Y W V U T R P N M L K J H G F E D C B A

0.635

(24.13)

19X 1.27

0.635

(24.13)

272X ⌀0.9
0.6

3

⌖ ⌀ 0.3Ⓜ A B C
⌀ 0.15Ⓜ A

BOTTOM VIEW

1.25
1.05

0.7
0.5

0.7
0.5

2.65
2.05

SIDE VIEW

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	STANDARD: JEDEC MS-034 BAL-2	
	SOT698-2	11 MAR 2016

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M—1994.

3. (triangle) MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. (triangle) DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. PACKAGE CODES:
   5065 — 2 LAYER 272 PBGA
   5047 — 4 LAYER 272 TEPBGA
   5192 — 4 LAYER 272 TEPBGA PGE

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